

LEADED

BGA SOLDER PASTE

● ● ●
Sn63/Pb37

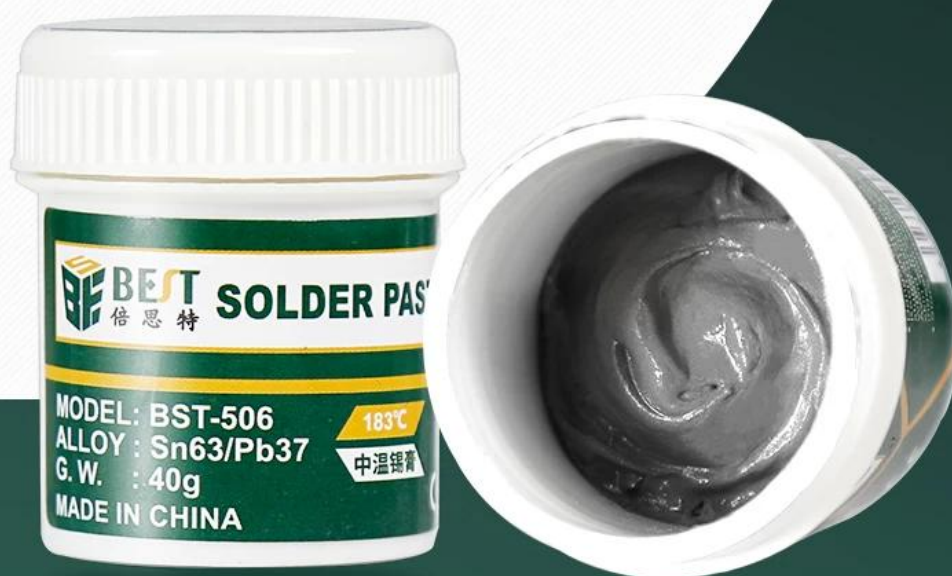
Melting point 183°C



Product Usage

● ● ●
TIN PASTE

Type number	BST-506
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	40g
size	38*32mm



Sn63/Pb37

Melting point at medium temperature

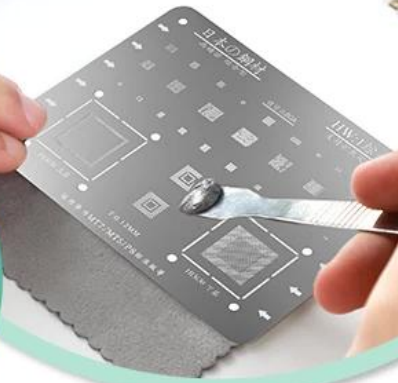
183°C



Low residue



Solder spot bright



Rapid welding



Welding requirements for a wide range of products



**SMT
patch**



**LED
patch**



**BGA
welding**



Product List

G.W.:40g

